

Abstract

System for manipulating singulated integrated circuit elements

A substrate dicing system includes a dicing machine (Z) which singulates integrated circuits formed within a substrate. The integrated circuits have
5 electrical contacts which face away generally upwardly during the dicing operation. Following the dicing the singulated units are placed onto a flipper block (8a), which is rotated so that the singulated units (7a) are inverted. The singulated units (7a) are removed from the flipper block (8a) by an idle unit (9). In subsequent processing steps, the singulated units (7a) can be retained
10 by suction applied to their upper surface without risk of damage to their electrical contacts.

[Fig. 1]



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